Notice of References Cited Application/Control No. | Applicant(s)/Patent Under Reexamination KAWACHI ET AL. | Examiner | Art Unit | Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-2003/0080832	05-2003	Enshasy, Hesham M.	333/193
	В	US-6,621,379	09-2003	Goetz et al.	333/193
	ပ	US-6,822,326	11-2004	Enquist et al.	257/729
	D	US-6,114,635	09-2000	Lakin et al.	174/260
	Е	US-6,445,265	09-2002	Wright, Peter	333/193
	F	US-6,853,067	02-2005	Cohn et al.	257/704
	G	US-5,847,489	12-1998	Satoh et al.	310/348
	H	US-			
	ı	US-			
	J	US-			
	К	US-		•	
	L	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	0 609 062 A1	08-1994	EPO	Kong et al.	***************************************
	0	JP 2000-68785	03-2000	Japan	Ohashi et al.	
	Р	JP 8-330894	12-1996	Japan	Egara et al.	
	Q	JP 5-235688	09-1993	Japan	Yuhara et al.	333/193
	R					•
	S	·				
	Т				`	

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)				
	U	Takagi et al. "Wafer-Scale Room-Temperature Bonding Between Silicon And Ceramic Wafers By Means Of Argon-Beam Surface Activation", The 14th Conference on Micro Electro Mechanical Systems 2001, MEMS 2001, pp. 60-63, January 2001.				
	٧					
	w					
	х					

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.